

CMOS MMIC 4 x 2 IF SWITCH MATRIX

FEATURES

NEC

- · 4 independent IF channels, integral switching to channel input to either channel output
- Integrated 4 bit decoder
- Frequency range : f = 250 to 2 150 MHz
- High isolation D/U ratio : ISL = 29 dB TYP.
- Insertion loss : LINS = 6.7 dB TYP. $@Z_0 = 50 \Omega$
- Insertion loss flatness $\therefore \Delta L_{INS} = 0.7 \text{ dB TYP}.$
- Control voltage : VCONT = 0 V/+3.3 V
- 16-pin plastic HTSSOP package

APPLICATIONS

- DBS IF switching
- Switch box
- 4×2 switching application for microwave signal

ORDERING INFORMATION

Part Number	Order Number	Package	Marking	Supplying Form
μPD5715GR-E1	μPD5715GR-E1-A	16-pin plastic HTSSOP (Pb-Free)		 Embossed tape 12 mm wide Pin 8, 9 face the perforation side of the tape Qty 3 kpcs/reel

Remark To order evaluation samples, contact your nearby sales office. Part number for sample order: μ PD5715GR

Caution Observe precautions when handling because these devices are sensitive to electrostatic discharge.

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ABSOLUTE MAXIMUM RATINGS (TA = +25°C, unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Supply Voltage	VDD	+4.6	V
Switch Control Voltage 1 to 4	VCONT1 to 4	+4.6	V
Total Power Dissipation	Ptot	2 Note	W
Input Power	Pin	+15	dBm
Operating Ambient Temperature	TA	-40 to +85	°C
Storage Temperature	Tstg	-65 to +150	°C

Note Mounted on double-sided copper-clad $50 \times 50 \times 1.6$ mm epoxy glass PWB, T_A = +85°C

RECOMMENDED OPERATING CONDITIONS (TA = +25°C)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Supply Voltage	VDD	+3.0	+3.3	+3.6	V
Control Voltage (H) Note	VCONT (H)	+3.0	+3.3	+3.6	V
Control Voltage (L)	VCONT (L)	-0.2	0	+0.4	V

Note V_{DD} -0.4 V $\leq V_{\text{CONT (H)}} \leq V_{\text{DD}}$ +0.2 V

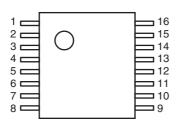
ELECTRICAL CHARACTERISTICS (TA = +25°C, VDD = +3.3 V, VCONT = 0 V/+3.3 V, Pin = 0 dBm, Zo = 50 Ω , each port, unless otherwise specified)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Insertion Loss	Lins	f = 0.25 to 2.15 GHz	-	6.7	9.0	dB
Insertion Loss Flatness	⊿Lins	LINS (0.95 GHz) — LINS (2.15 GHz)	-	0.7	3.0	dB
Isolation D/U-ratio1 Note 1	ISL1	f = 0.25 to 0.95 GHz	28	34	_	dB
Isolation D/U-ratio2 Note 1	ISL2	f = 0.95 to 2.15 GHz	25	29	-	dB
Output Return Loss	RLout	f = 0.25 to 2.15 GHz	10	13	-	dB
Control Current Note 2	Ісонт	V _{DD} = +3.3 V, V _{CONT} = +3.3 V/0 V, non-RF	-	0.01	1	μA
Supply Current	ldd	V _{DD} = +3.3 V, V _{CONT} = +3.3 V/0 V, non-RF	-	0.01	1	μA

Notes 1. Isolation Desire Un-desire (D/U)-ratio = |(Signal leakage (off-state)) – (Insertion loss (on-state))|
2. Per 1 control pin

PIN CONNECTIONS

(Top View)



Pin No.	Pin Name	Pin No.	Pin Name
1	IN-C	16	IN-B
2	GND	15	GND
3	IN-D	14	IN-A
4	GND	13	GND
5	GND	12	Vdd
6	OUT2	11	OUT1
7	VCONT3	10	VCONT1
8	Vcont4	9	VCONT2

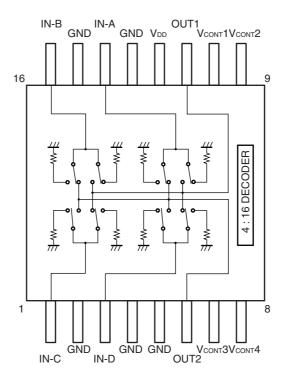
Remark Back side. : GND

TRUTH TABLE

State		Output	Signal	Control Pins			
No.	Mode	OUT1	OUT2	Vcont1	VCONT2	Vcont3	Vcont4
1	AA	IN-A	IN-A	Low	Low	Low	Low
2	AB		IN-B	Low	Low	Low	High
3	AC		IN-C	Low	Low	High	Low
4	AD		IN-D	Low	Low	High	High
5	BA	IN-B	IN-A	Low	High	Low	Low
6	BB		IN-B	Low	High	Low	High
7	BC		IN-C	Low	High	High	Low
8	BD		IN-D	Low	High	High	High
9	CA	IN-C	IN-A	High	Low	Low	Low
10	СВ		IN-B	High	Low	Low	High
11	СС		IN-C	High	Low	High	Low
12	CD		IN-D	High	Low	High	High
13	DA	IN-D	IN-A	High	High	Low	Low
14	DB		IN-B	High	High	Low	High
15	DC		IN-C	High	High	High	Low
16	DD		IN-D	High	High	High	High

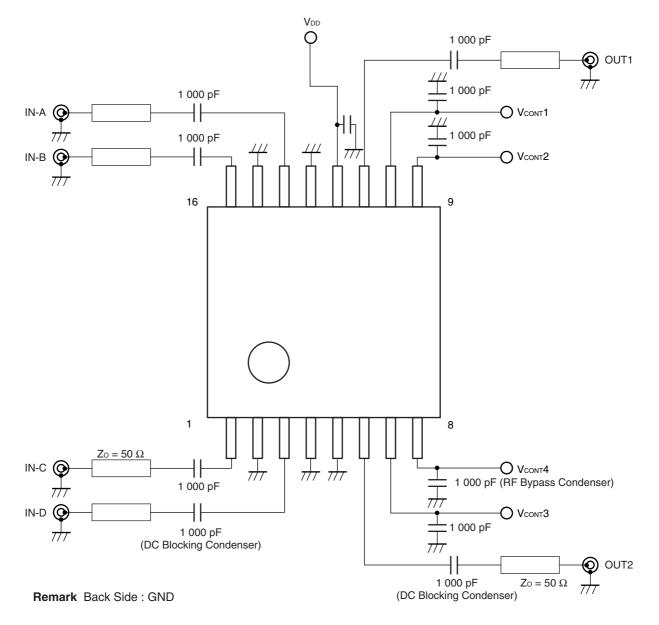
Remark High : +3.3 Vdc, Low : 0 Vdc

FUNCTIONAL DIAGRAM



Remark Back Side : GND

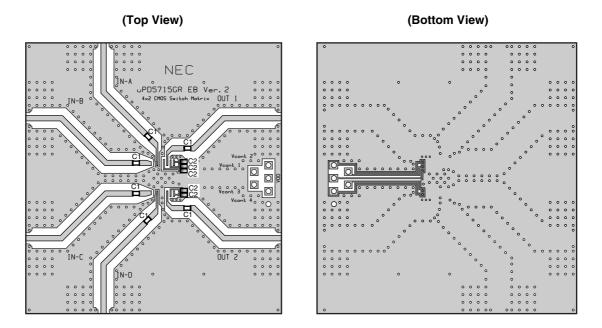
Data Sheet PU10601EJ01V0DS



EVALUATION CIRCUIT (VDD = +3.3 V, VCONT1 to VCONT4 = 0 V/+3.3 V, Pin = 0 dBm, Zo = 50 Ω , DC Blocking Capacitor = 1 000 pF)

The application circuits and their parameters are for reference only and are not intended for use in actual design-ins.

ILLUSTRATION OF THE TEST CIRCUIT ASSEMBLED ON EVALUATION BOARD

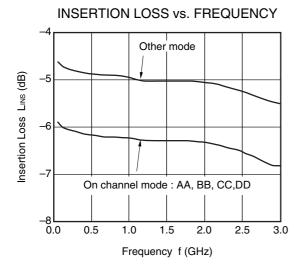


Notes

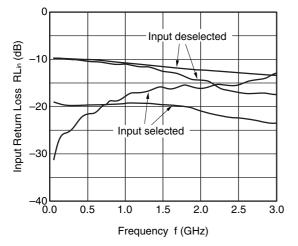
- 1. $50 \times 53 \times 0.51$ mm double sided copper clad RO4003 (Rogers) board (*e*r = 3.38).
- 2. Au plated on pattern
- 3. oO: Through holes
- 4. C1, C2: 1 000 pF

TYPICAL CHARACTERISTICS

(TA = +25°C, VDD = +3.3 V, VCONT = 0 V/+3.3 V, Pin = 0 dBm, Zo = 50 Ω , unless otherwise specified)



INPUT RETURN LOSS vs. FREQUENCY

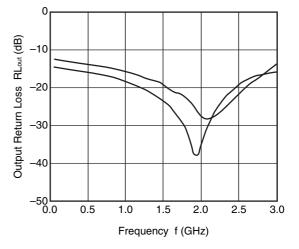


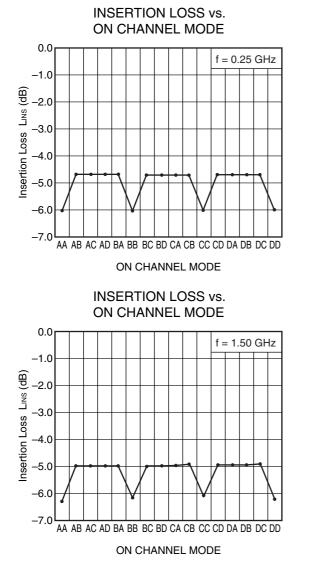
Remark The graphs indicate nominal characteristics.

SIGNAL LEAKAGE vs. FREQUENCY

OUTPUT RETURN LOSS vs. FREQUENCY

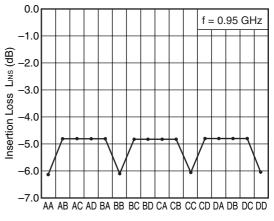
Frequency f (GHz)





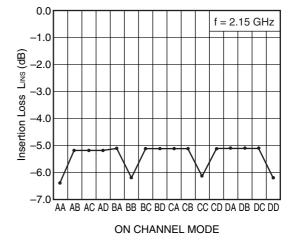
Remark The graphs indicate nominal characteristics.

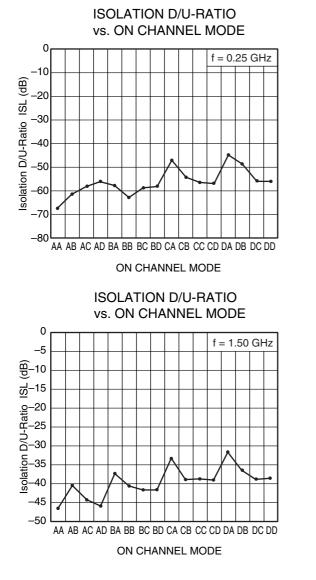
INSERTION LOSS vs. ON CHANNEL MODE



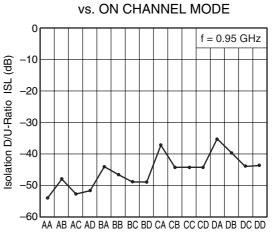
ON CHANNEL MODE

INSERTION LOSS vs. ON CHANNEL MODE





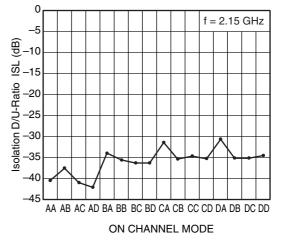
Remark The graphs indicate nominal characteristics.

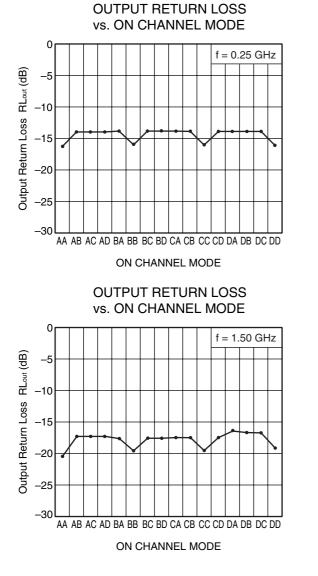


ISOLATION D/U-RATIO

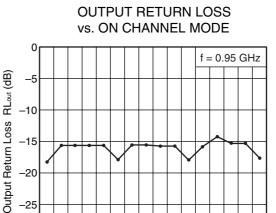
ON CHANNEL MODE

ISOLATION D/U-RATIO vs. ON CHANNEL MODE





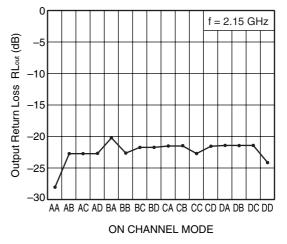
Remark The graphs indicate nominal characteristics.



AA AB AC AD BA BB BC BD CA CB CC CD DA DB DC DD ON CHANNEL MODE

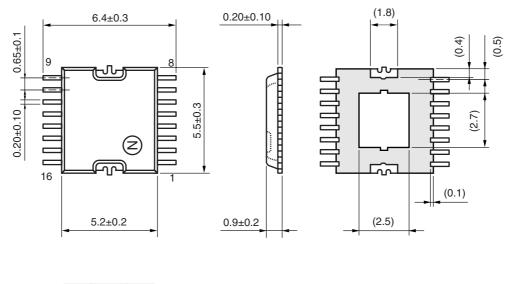
-30

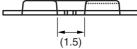
OUTPUT RETURN LOSS vs. ON CHANNEL MODE



PACKAGE DIMENSIONS

16-PIN PLASTIC HTSSOP (UNIT: mm)





RECOMMENDED SOLDERING CONDITIONS

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions	Condition Symbol	
Infrared Reflow	Peak temperature (package surface temperature) Time at peak temperature Time at temperature of 220°C or higher Preheating time at 120 to 180°C Maximum number of reflow processes Maximum chlorine content of rosin flux (% mass)	: 260°C or below : 10 seconds or less : 60 seconds or less : 120±30 seconds : 3 times : 0.2%(Wt.) or below	IR260
Partial Heating	Peak temperature (terminal temperature) Soldering time (per side of device) Maximum chlorine content of rosin flux (% mass)	: 350°C or below : 3 seconds or less : 0.2%(Wt.) or below	HS350

Caution Do not use different soldering methods together (except for partial heating).

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